

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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300mW, NPN Small Signal Transistor

FEATURES

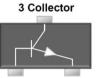
- Epitaxial planar die construction
- Surface device type mounting
- Moisture sensitivity level 1
- Matte Tin (Sn) lead finish with Nickel (Ni) underplate
- Pb free version and RoHS compliant
- Packing code with suffix "G" means green compound (halogen-free)

MECHANICAL DATA

- Case: SOT- 23, molded plastic
- Terminal: Matte tin plated, lead free, solderable per MIL-STD-202, Method 208 guaranteed
- High temperature soldering guaranteed: 260°C/10s
- Weight: 0.008g (approximately)
- Marking Code: 1AM







1 Base 2 Emitter





MAXIMUM RATINGS AND ELECTRICAL CHARACTERSTICS (T _A =25°C unless otherwise noted)					
PARAMETER	SYMBOL	VALUE	UNIT		
Power Dissipation	P_D	300	mW		
Collector-Base Voltage	V_{CBO}	60	V		
Collector-Emitter Voltage	V_{CEO}	40	V		
Emitter-Base Voltage	V_{EBO}	6	V		
Collector Current	I _C	200	mA		
Junction and Storage Temperature Range	T_J,T_STG	-55 to +150	°C		

Notes:1. Valid provided that electrodes are kept at ambient temperature

PARAMETER				SYMBOL	MIN	MAX	UNIT
Collector-Base Breakdow	vn Voltage	I _C = 10 μA	I _E = 0	V _{(BR)CBO}	60	-	V
Collector-Emitter Breakdo	own Voltage	$I_C = 1 \text{ mA}$	I _B = 0	V _{(BR)CEO}	40	-	V
Emitter-Base Breakdown	Voltage	I _E = 10 μA	I _C = 0	$V_{(BR)EBO}$	6	-	V
Collector Cut-off Current		V _{CB} = 60 V	I _E = 0	I _{CBO}	-	0.1	μA
Collector Cut-off Current		V _{CE} = 30 V	$V_{BE(OFF)} = 3 V$	I _{CEO}	-	50	nA
Emitter Cut-off Current		V _{EB} = 5 V	I _C = 0	I _{EBO}	-	0.1	μA
		V _{CE} = 1 V	I _C = 10 mA		100	400	
DC Current Gain		$V_{CE} = 1 V$	$I_C = 50 \text{ mA}$	h_{FE}	60	-	
		$V_{CE} = 1 V$	$I_{\rm C}$ = 100 mA		30	-	
Collector-Emitter Saturat	ion Voltage	$I_C = 50 \text{ mA}$	I _B = 5 mA	V _{CE(sat)}	-	0.3	V
Base-Emitter Saturation Voltage		$I_C = 50 \text{ mA}$	I _B = 5 mA	$V_{BE(sat)}$	-	0.95	V
Transition frequency	V _{CE} = 20 V	I_C = 10 mA	f= 100MHz	f _T	250	-	MHz
Delay time	V _{CC} = 3 V	V _{BE} = 0.5 V	I _C = 10 mA	t _d	-	35	ns
Rise time			$I_{B1} = 1.0 \text{ mA}$	t _r	-	35	ns
Storage time		V _{CC} = 3 V	I _C = 10 mA	t _s	-	200	ns
Fall time		$I_{B1} = I_{B2} = 1.0$	mA	t _f	-	50	ns

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RATINGS AND CHARACTERISTICS CURVES

(T_A=25°C unless otherwise noted)

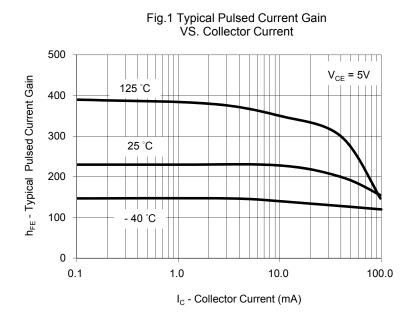


Fig. 2 Collector-Emitter Saturation Voltage VS. Collector Current

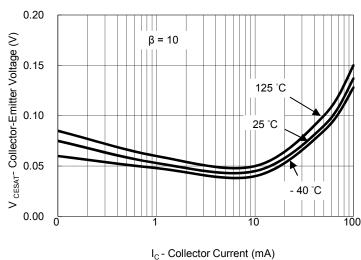


Fig. 3 Base-Emitter Saturation Voltage VS. Collector Current

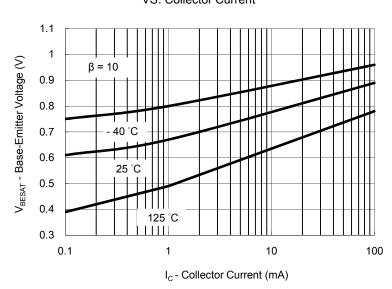


Fig. 4 Base-Emitter On Voltage VS. Collector Current

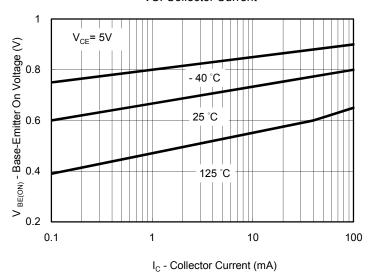


Fig. 5 Collector-Cutoff Current VS. Ambient Temperature

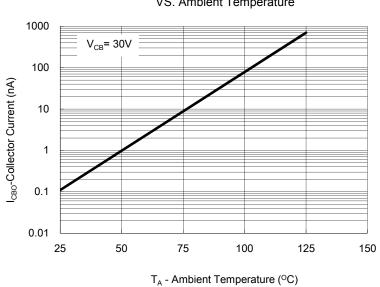
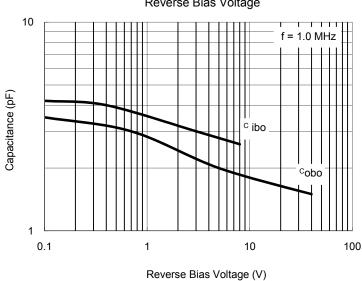


Fig. 6 Capacitance VS. Reverse Bias Voltage



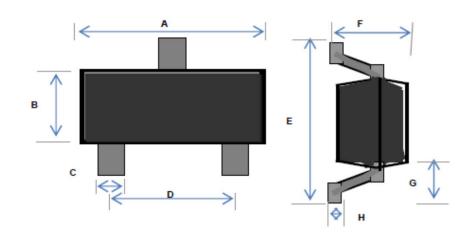


ORDERING	ORDERING INFORMATION					
PART NO.	PART NO. SUFFIX (Note 1)	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING	
MMBT3904	-XX	RF	G	SOT-23	3K / 7" Reel	
101101513904	-44	R5	9		10K / 13" Reel	

Note 1: Part No. Suffix "-xx " would be used for special requirement

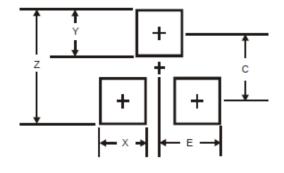
EXAMPLE					
PREFERRED P/N	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
MMBT3904 RF	MMBT3904		RF		Multiple manufacture source
MMBT3904 RFG	MMBT3904		RF	G	Multiple manufacture source Green compound
MMBT3904-D0 RFG	MMBT3904	-D0	RF	G	Defined manufacture source Green compound
MMBT3904-B0 RFG	MMBT3904	-B0	RF	G	Defined manufacture source Green compound

PACKAGE OUTLINE DIMENSIONS



DIM.	Unit(mm)	Unit(inch)	
DIIVI.	Min	Max	Min	Max
Α	2.70	3.10	0.106	0.122
В	1.10	1.50	0.043	0.059
С	0.30	0.51	0.012	0.020
D	1.78	2.04	0.070	0.080
E	2.10	2.64	0.083	0.104
F	0.89	1.30	0.035	0.051
G	0.55 REF		0.022	REF
Н	0.10 REF		0.004	REF

SUGGEST PAD LAYOUT



DIM	Unit (mm)	Unit (inch)	
DIIVI	TYP	TYP	
Z	2.8	0.11	
Х	0.7	0.03	
Υ	0.9	0.04	
С	1.9	0.07	
Е	1.0	0.04	





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